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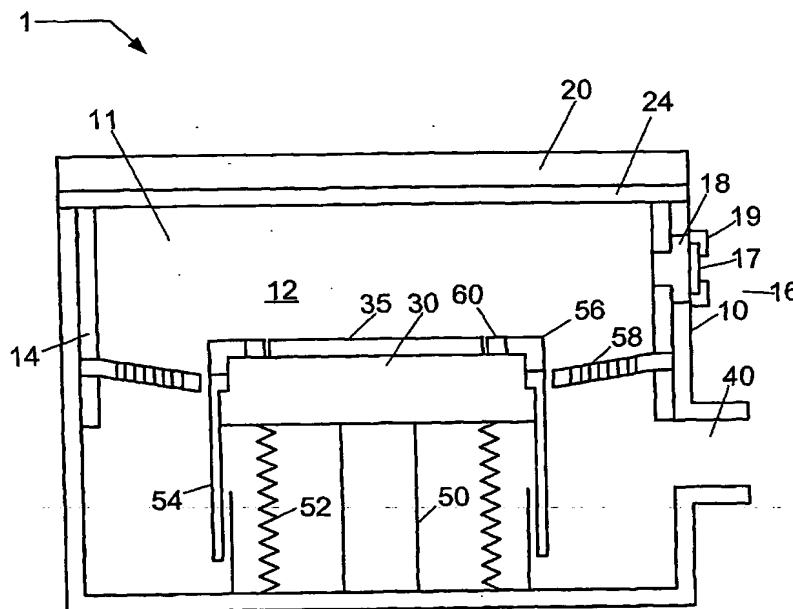
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[Continued on next page]

(54) Title: METHOD AND APPARATUS FOR REDUCING SUBSTRATE BACKSIDE DEPOSITION DURING PROCESSING



(57) Abstract: A focus ring assembly configured to be coupled to a substrate holder comprises a focus ring and a secondary focus ring coupled to the focus ring, wherein the secondary focus ring is configured to reduce the deposition of process residue on a backside surface of the substrate.

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